

## Description

### N-channel Enhancement Mode Power MOSFET

#### Features

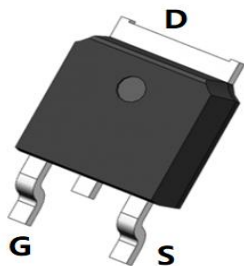
- 100V, 15A  
 $R_{DS(ON)}$  Typ= 86m $\Omega$  @  $V_{GS}$  = 10V  
 $R_{DS(ON)}$  Typ= 96m $\Omega$  @  $V_{GS}$  = 4.5V
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge

#### Applications

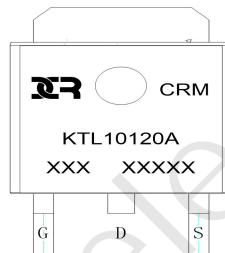
- Load Switch
- PWM Application
- Power Management



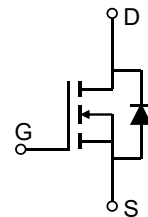
100% UIS TESTED!  
100%  $\Delta V_{ds}$  TESTED!



TO-252-3L



Marking and Pin Assignment



Schematic Diagram

### Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
CRMKTL10120A	CRMKTL10120A	TAPING	TO-252-3L	13"	2500	25000

### Absolute Maximum Ratings (@ $T_J$ = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	60	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	12	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	$^\circ\text{C/W}$
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$



## Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.5	2.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A	-	86.0	108.0	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A	-	96.0	125.0	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1MHz	-	847	-	pF
C <sub>oss</sub>	Output Capacitance		-	40	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	12	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 50V, I <sub>D</sub> = 2A	-	20	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	2.8	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	4	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V I <sub>D</sub> = 3A, R <sub>GEN</sub> =1.8Ω	-	6	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	7	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	21	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	3	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	15	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	60	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 10A, di/dt = 100A/us	-	22	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	29	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
  2. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω, I<sub>AS</sub>=7A
  3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

## Typical Performance Characteristics

Figure 1: Output Characteristics

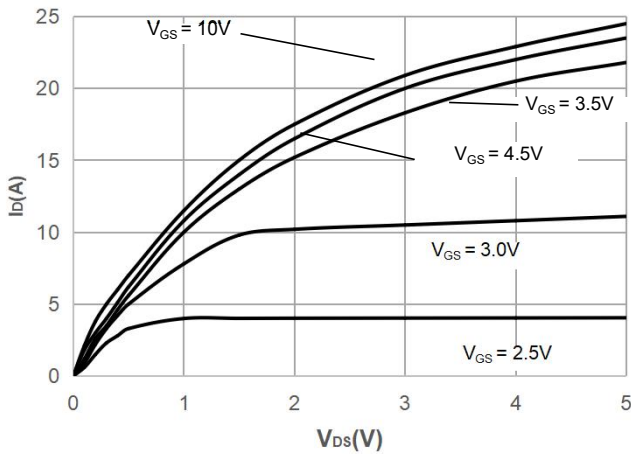


Figure 2: Typical Transfer Characteristics

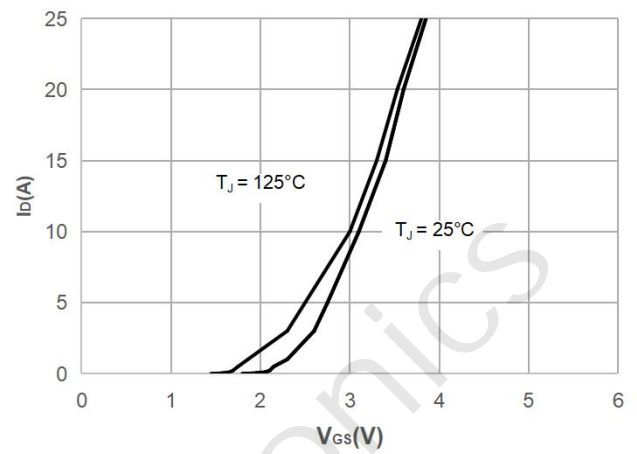


Figure 3: On-resistance vs. Drain Current

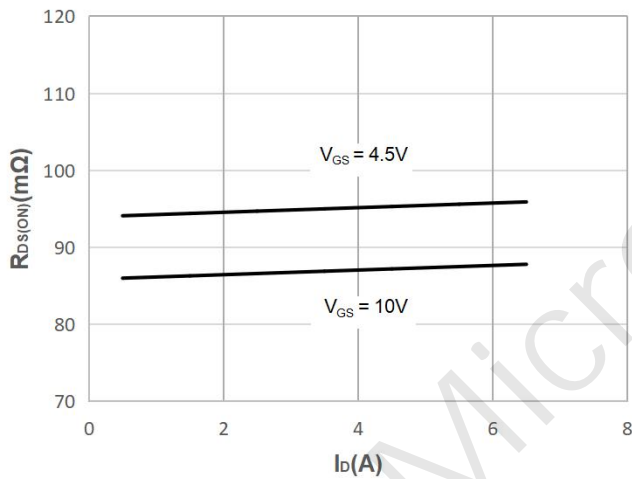


Figure 4: Body Diode Characteristics

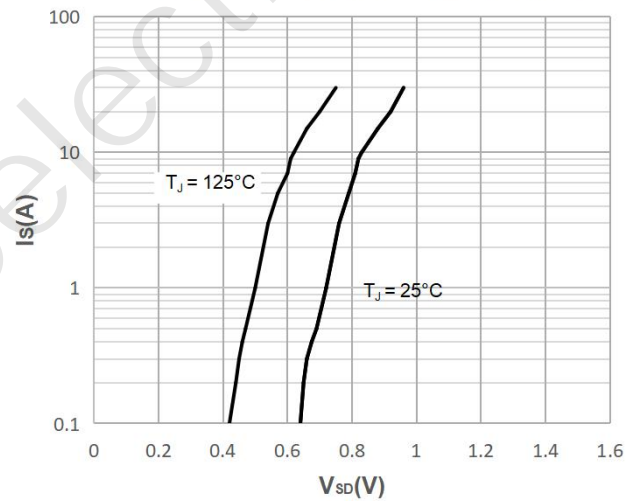


Figure 5: Gate Charge Characteristics

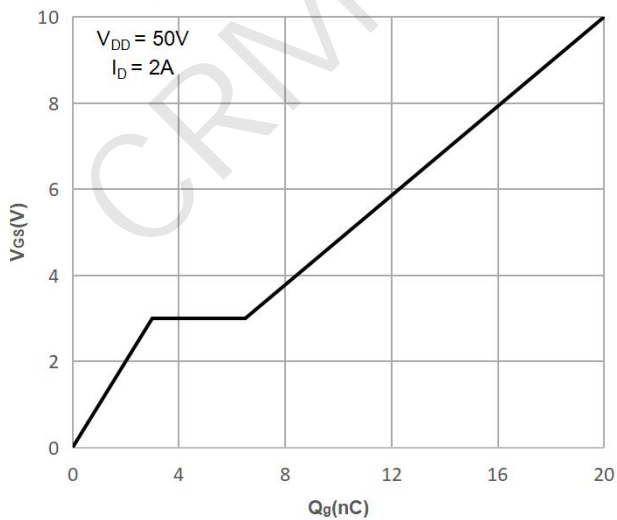
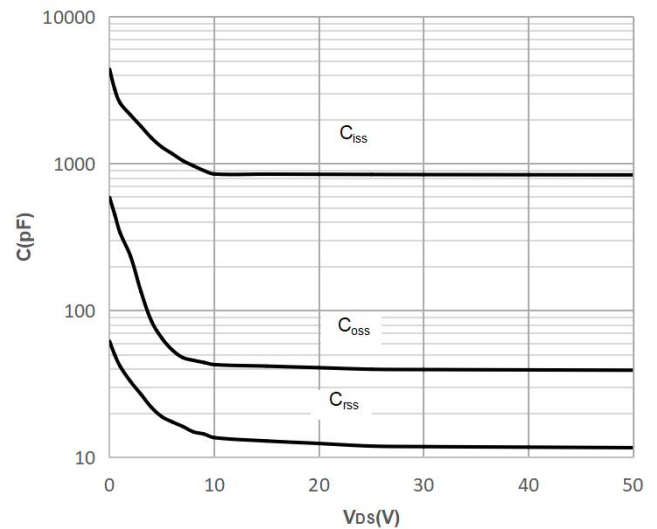


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

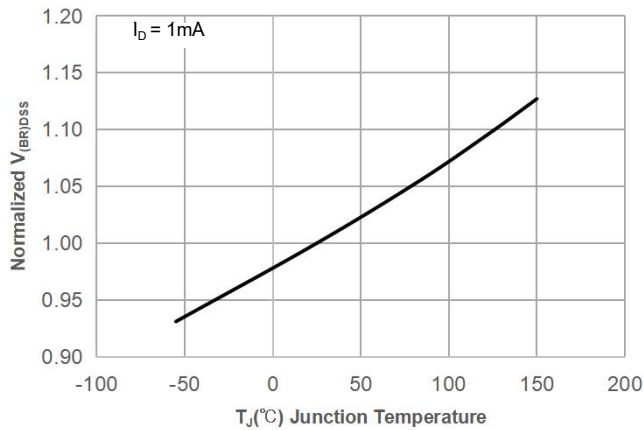


Figure 8: Normalized on Resistance vs. Junction Temperature

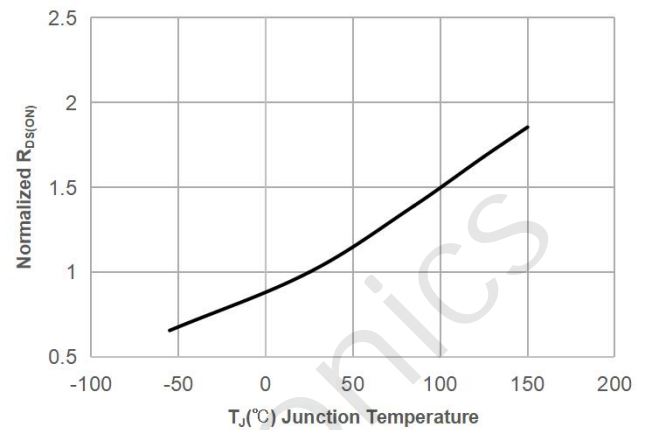


Figure 9: Maximum Safe Operating Area

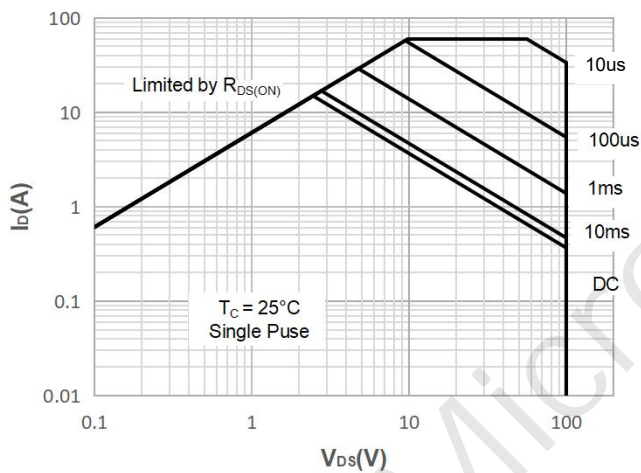


Figure 10: Maximum Continuous Driain Current vs. Case Temperature

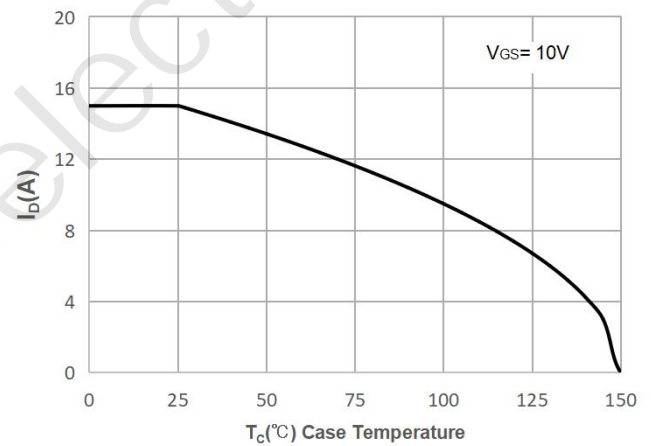


Figure 11: Normalized Maximum Transient Thermal Impedance

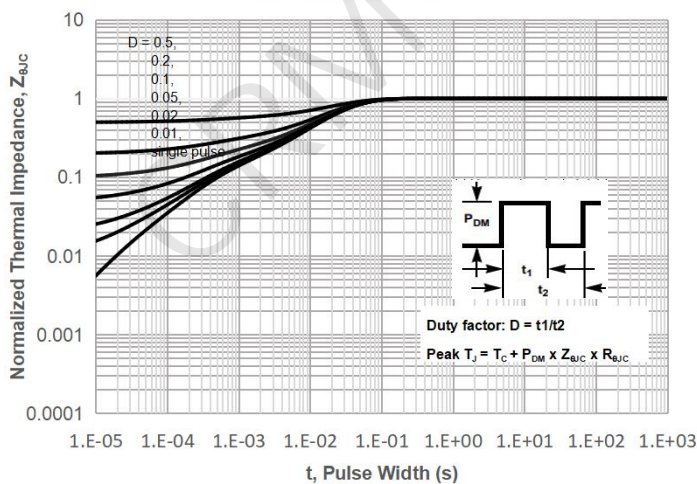
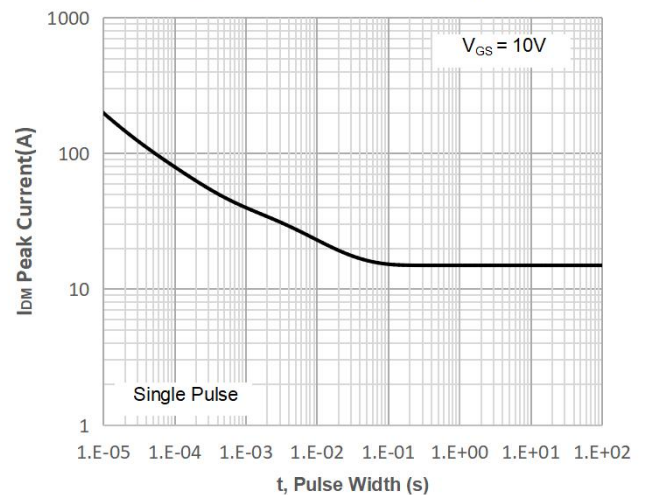


Figure 12: Peak Current Capacity



## Test Circuit

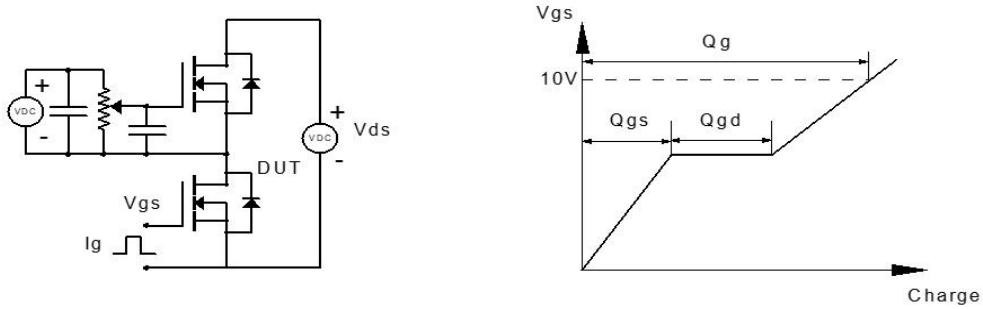


Figure 1: Gate Charge Test Circuit & Waveform

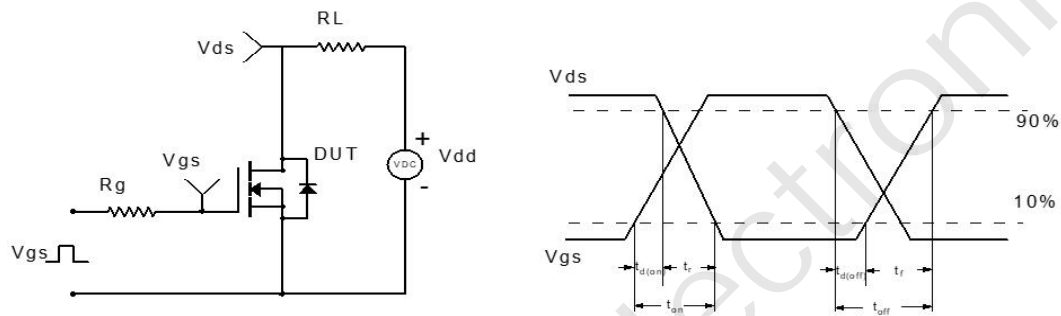


Figure 2: Resistive Switching Test Circuit & Waveform

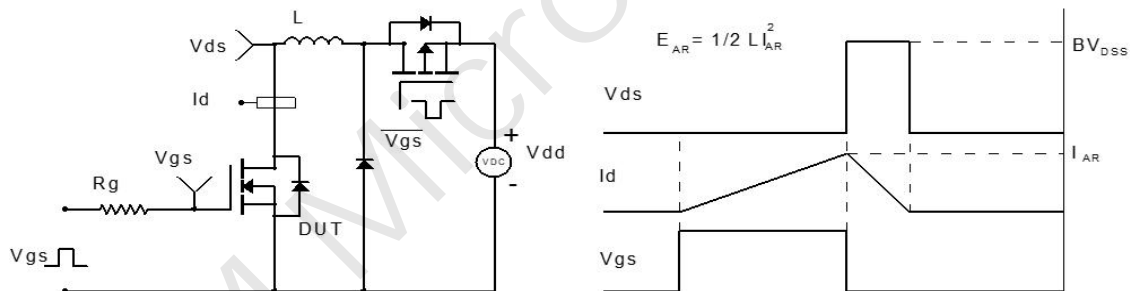


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

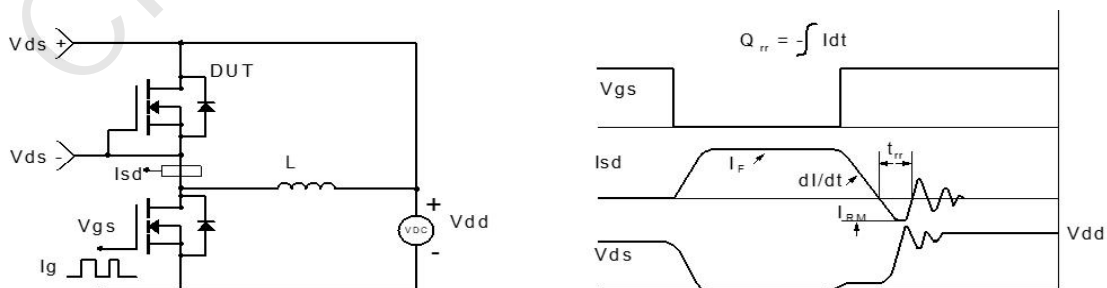
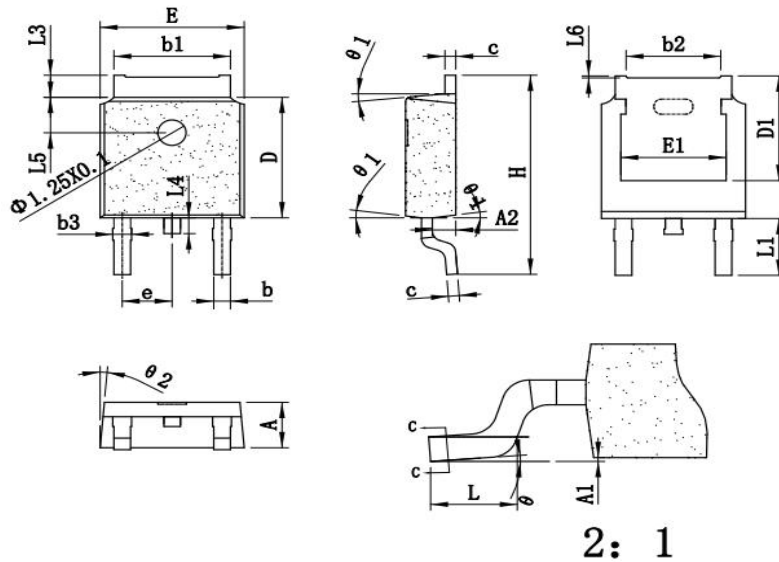


Figure 4: Diode Recovery Test Circuit & Waveform

## Package Mechanical Data(TO-252-3L)



SYMBOL	mm		
	MIN	NOM	MAX
*A	2.20	2.30	2.38
*A1	0.00	—	0.15
*A2	0.90	1.00	1.10
*b	0.72	0.78	0.85
b1	5.23	5.33	5.46
b2	4.05	4.20	4.35
*b3	0.78	0.85	0.90
*c	0.47	0.52	0.55
*D	6.00	6.10	6.20
D1	5.40REF		
*E	6.50	6.60	6.70
E1	4.70	4.83	4.92
*e	2.286BSC		
*H	9.90	10.10	10.20
*L	1.40	1.55	1.70
L1	2.90REF		
L3	0.90	—	1.20
L4	0.75	0.85	0.95
L5	1.70	1.80	1.90
L6	0.00	0.06	0.12
*θ	0°	—	5°
θ1	5°	7°	9°
θ2	5°	7°	9°

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